

L Number	Hits	Search Text	DB	Time stamp
1	134	(low near resistance)and ( interconnect near line)and ( cooper or Cu) and ( Aluminum or Al)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 17:26
7	252	(low near resistance)and ( interconnect near line)and ( copper or Cu) and ( Aluminum or Al)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 17:27
13	230	(low near resistance)and ( interconnect near line)and ( Aluminum or Al)and over and ( copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 17:34
19	88	(low near resistance)and ( interconnect near line)and ( Aluminum or Al)same over same ( copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:03
25	2	(low near resistance)and ( interconnect near line)and ( Aluminum or Al)near over near ( copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 17:40
31	117	"5262354"	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 17:50
37	0	(low near resistance)and ( interconnect near line)and ( Aluminum or Al)adj over adj ( copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:06
43	593	(low near resistance)and ( interconnect near line)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:06
55	0	((low near resistance)and ( interconnect near line)) and (( Aluminum or Al)adj over adj ( copper or Cu))	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:06
49	15	( Aluminum or Al)adj over adj ( copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:35
61	14123	( Aluminum or Al)with( over or above) with ( copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:37
67	14747	43and (( Aluminum or Al)with( over or above) with ( copper or Cu))	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:37
73	4519	( Aluminum or Al)with( over ) with ( copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:38
79	41	((low near resistance)and ( interconnect near line)) and (( Aluminum or Al)with( over ) with ( copper or Cu))	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:46
85	21755	Semiconductor and via and (copper or Cu) and ( aluminum or Al)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:49
91	19755	Semiconductor and via and( aluminum or Al) and (above) and ( copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:50
97	2278	Semiconductor and via and( aluminum or Al) and (above) and ( copper or Cu) and ( low near resistance)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:56

103	7184	interconnect near line	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:52
109	149	(Semiconductor and via and( aluminum or Al) and (above) and ( copper or Cu) and ( low near resistance)) and (interconnect near line)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:54
115	21	Semiconductor and via and( aluminum or Al) adj (above) and ( copper or Cu) and ( low near resistance)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:58